Title (en)

Method for manufacturing a component having a damping structure

Title (de)

Verfahren zum Herstellen einer Komponente mit einer Dämpfstruktur

Title (fr)

Procédé de fabrication d'un composant ayant une structure d'amortissement

Publication

EP 2792434 A1 20141022 (EN)

Application

EP 13164577 A 20130419

Priority

EP 13164577 A 20130419

Abstract (en)

A method for manufacturing a component (1) having an internal damping structure (2) is disclosed. The method comprising the following steps: a) providing core parts (3, 3'), made of a first material with a melting point higher than the manufacturing process temperature, b) arranging the core parts (3,3') in a cast mould in a pattern for receiving a desired internal damping structure (2), c) providing and melting a base material (4), the base material (4) having different physical properties, at least a lower melting point then the first material, then d) casting the component (1) by using the molten base material (4), the base material surrounding the core parts (3,3'), then e) solidification of the base material (4), then f) removing the cast mould, then g) optionally removing a part (3) of the core parts.

IPC 8 full level

B22C 9/10 (2006.01); **B22D 19/04** (2006.01); **F01D 5/18** (2006.01)

CPC (source: EP)

B22C 9/103 (2013.01); **B22C 9/108** (2013.01); **B22D 19/04** (2013.01); F01D 5/16 (2013.01); F05D 2230/21 (2013.01)

Citation (applicant)

- US 6827551 B1 20041207 - DUFFY KIRSTEN P [US], et al
- US 6224341 B1 20010501 - FRICKE J ROBERT [US]

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- [X] US 2009020256 A1 20090122 - HANNA MICHAEL D [US], et al
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- [A] EP 2161411 A1 20100310 - SIEMENS AG [DE]

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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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DOCDB simple family (application)

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